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In re Patent Application of: )  
SMYTH ET AL. )  
Serial No. 10/022,595 )  
Confirmation No. 5966 )  
Filing Date: DECEMBER 13, 2001 )  
For: ELECTRONIC MODULE INCLUDING A )  
LOW TEMPERATURE CO-FIRED )  
CERAMIC (LTCC) SUBSTRATE WITH )  
A CAPACITIVE STRUCTURE EMBEDDED )  
THEREIN AND RELATED METHODS )

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TRANSMITTAL OF FORMAL DRAWINGS

Director, U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

Enclosed are four (4) sheets of formal drawings to be  
filed in the above-identified patent application.

Respectfully submitted,

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